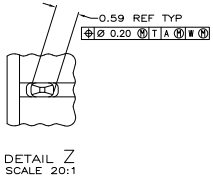
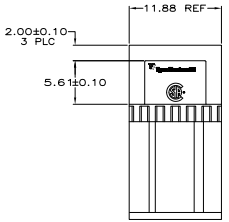
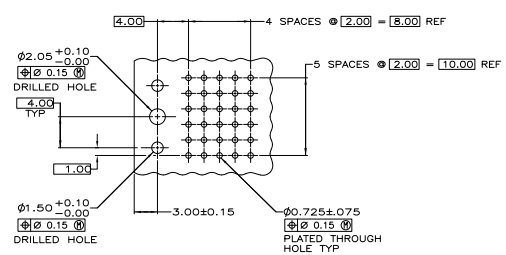
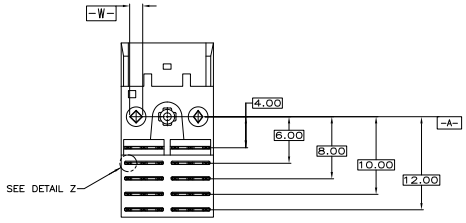
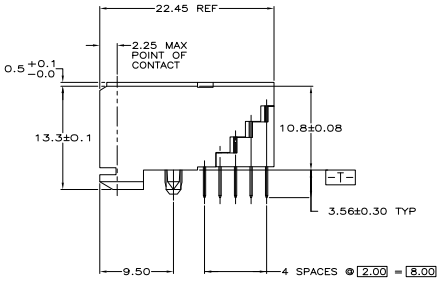
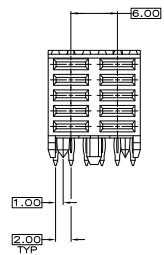


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REV	DATE	DESCRIPTION	BY	CHK	APP
AD 00					
01		REVISED PER ECO-08-009182	22APR08	DH	AS



△ HOUSINGS MATERIAL: LIQUID CRYSTAL POLYMER.  
 △ CONTACT MATERIAL: COPPER ALLOY.  
 △ CONTACT FINISH:(D)  
 UNDERPLATE (ENTIRE CONTACT):  
 0.00127 MIN NICKEL PER SAE-AMS-QQ-N-290  
 ON MATING SURFACES:  
 FLASH GOLD PER ASTM B 488, OVER  
 0.00076 MIN PALLADIUM-NICKEL OVER UNDERPLATE, OR  
 0.00076 MIN GOLD PER ASTM B 488 OVER UNDERPLATE.  
 ON LEADS:  
 0.00127 MIN MATTE TIN PER ASTM B 545 OVER UNDERPLATE.  
 LUBRICATION (MIN MATING SURFACES):  
 SURFACE CONDITIONER AFTER PLATING.



RECOMMENDED CIRCUIT PATTERN  
 PER IPC-D300 TYPE II, CLASS C  
 (COMPONENT SIDE)

FINISH	5536676-1
PART NUMBER	

THIS DRAWING IS A CONTROLLED DOCUMENT.		BY: SHEELY 8/29/98	DATE: 8/29/98	REV: 1	DATE: 8/29/98
DRAWN BY: KUNZLECK 8/29/98		DATE: 8/29/98	REV: 1	DATE: 8/29/98	REV: 1
CHECKED BY: KUNZLECK 8/29/98		DATE: 8/29/98	REV: 1	DATE: 8/29/98	REV: 1
APPROVED BY: KUNZLECK 8/29/98		DATE: 8/29/98	REV: 1	DATE: 8/29/98	REV: 1
CUSTOMER DRAWING		SIZE: A1	DATE: 00779	Q=5536676	REVISED TO: 01